

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of )  
Yamazaki et al. )  
Serial No.: )  
Filed: Herewith )  
For: Wiring Material And A )  
Semiconductor Device Having A )  
Wiring Using the Material, And The )  
Manufacturing Method Thereof )  
Art Unit: )  
Examiner: )

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Date of Deposit July 29, 2003

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Name: Yue X Ruan  
(typed or printed)

Signature Yue X Ruan

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT A**

Sir:

Prior to examination and calculation of the fees, please amend the above-identified application as follows: